



SPECIFICATIONS	

CUSTOMER	: PIC
SAMPLE CODE	SH240320T-062-L06Q
MASS PRODUCTION CODE	PH240320T-062-L06Q
SAMPLE VERSION	<u> </u>
SPECIFICATIONS EDITION	005
DRAWING NO.	JLMD- PH240320T-062-L06Q_001
PACKAGING NO.	JPKG- PH240320T-062-L06Q_001

Customer Approved

Date:

Approved	Checked	Designer		
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Preliminary specification for design input

Specification for sample approval

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History of Version

Date	Ver.	Edi.	Description	Page	Design by
2012/08/31	01	001	New Drawing	-	趙冬冬
2012/11/29	01	002	New Sample	-	趙冬冬
2014/03/25	01	003	Change Viewing Angle & Contrast Ratio Show Refer Initial Code	6 14~16	劉進
2014/04/10	01	004	Change Viewing Angle	6	劉進
2015/08/24	01	005	Show Backlight Life Time	8	張斌
				Tota	al: 29 Page



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1. SPECIFICATIONS

1.1 Features

Main LCD Panel

Item	Standard Value
Display Type	240 * (R 、 G 、 B) * 320 Dots
LCD Type	a-Si TFT , Normally white TN mode , Transmissive
Screen size(inch)	2.4 (Diagonal)
Viewing Direction	12 O'clock
Color configuration	R.G.B. vertical stripe
Interface	16-bit interface for i80system
Other(controller / driver IC)	ILI9341
	THIS PRODUCT CONFORMS THE ROHS OF PTC
ROHS	Detail information please refer web side :
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	42.72 (W) * 60.26 (L) * 3.85(H)(max)	mm

LCD Panel

Item	Standard Value	Unit
Active Area	36.72 (W) * 48.96 (L)	mm

TP Panel

Item	Standard Value	
Viewing Area	38.32 (W)* 50.26 (L)(min)	
Active Area	37.52 (W) * 49.76 (L)	mm

Note : For detailed information please refer to LCM drawing



1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit
System Dower Supply Voltage	VDDI	-	-0.3	+4.6	V
System Power Supply Voltage	VGH-VGL	-	-0.3	+32.0	V
Input Voltage	VIN	-	-0.3	VDD+0.3	V
Operating Temperature	Top	-	-20	+70	°C
Storage Temperature	T _{ST}	-	-30	+80	°C
Storage Humidity	H⊳	Ta ≦ 60 °C	20	90	%RH

1.4 DC Electrical Characteristics

Module	GND = 0V, Ta = 25°C					
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage1	VDDI		2.5	2.8	3.3	V
Input High Voltage	Vін	-	0.7*VDDI	_	VDDI	V
Input Low Voltage	VIL	-	VSS	-	0.3*VDDI	V
Output High Voltage	Vон	IOH=-1.0 mA	0.8*VDDI	-	VDDI	V
Output Low Voltage	Vol	IOL=+1.0mA	VSS	-	0.2*VDDI	V
Supply Current	IDD	VDDI= 2.8V, Pattern=Black*1	-	7.7	12	mA

Note1 : Maximum current display



1.5 Optical Characteristics

TFT LCD Panel

VDDI = 2.8V, Ta=25°C

Item		Symbol	Condition	Min.	Тур.	Max.	unit	
Response tin	ne	Tr + Tf	Ta = 25°C θX, θY = 0•	-	25	38	ms	Note2
	Тор	θY+		-	45	-		
	Bottom	θY-	CR ≥ 10	-	15	-	Dog	Noto 4
Viewing angle	Left	θХ-	CR ≥ 10	-	45	-	Deg.	Note4
	Right	θX+		-	45	-		
Contrast rati	0	CR		150	200	-	-	Note3
	White	Х	Ta = 25°C θX , θY = 0•	0.23	0.28	0.33		
	vvnite	Y		0.25	0.30	0.35		
	Red	Х		0.53	0.58	0.63		
Color of CIE		Y		0.29	0.34	0.39		Niete 1
Coordinate (With B/L)	Croon	Х		0.27	0.32	0.37		Note1
(Green	Y		0.54	0.59	0.64		
	Dhuo	Х		0.09	0.14	0.19		
	Blue	Y		0.01	0.06	0.11		
Average Brightr	ness							
Pattern=white display		IV	IF=20mA	140	155	-	cd/m²	Note1
(With B/L)								
Uniformity (With B/L)		∆В	IF=20mA	80	-	-	%	Note1

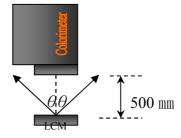
Note1:

 $1 : \triangle B = B(min) / B(max) \times 100\%$

2 : Measurement Condition for Optical Characteristics:

- a : Environment: 25°C ±5°C / 60±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
- b : Measurement Distance: 500 \pm 50 mm \rightarrow (θ = 0°)
- c : Equipment: TOPCON BM-7 fast , (field 1°) , after 10 minutes operation.
- d: The uncertainty of the C.I.E coordinate measurement ±0.01 · Average Brightness ± 4%





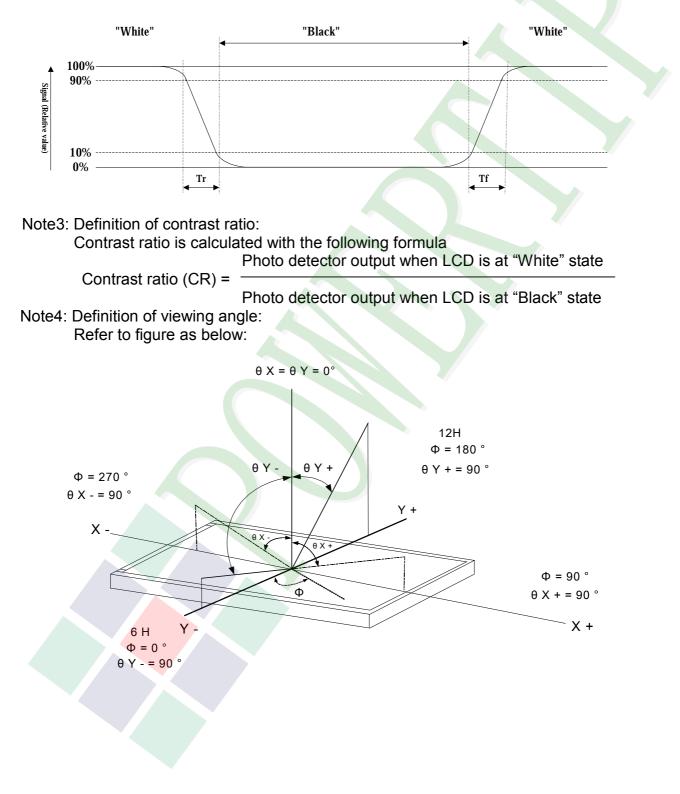
Colorimeter=BM-7 fast



Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:





1.6 Backlight Characteristics

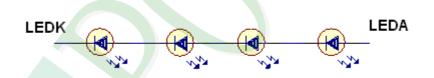
Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25 ℃	-	30	mA
Forward Voltage	VF	Ta =25℃	-	14.4	V
Reverse Voltage	VR	Ta =25℃	-	5	V

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=20mA	12.4	13.2	14.4	V
Average Brightness (without LCD & T/P)	IV		3800	4200	Y -	cd/m ²
Color of CIE Coordinate	Х	IF=20mA	0.25	0.28	0.31	
(without LCD & T/P)	Y		0.25	0.28	0.31	-
Color			White			

Internal Circuit Diagram



Other Description

Item	Conditions	Description
Life Time	Ta =25℃ IF= 20mA	20000 hrs



1.7 Touch Panel Characteristics

1.7.1 General Standard Specification

Item	Specification
Input Method	Finger or Stylus pen.
ITO Glass	400±100 Ω Glass.
ITO Film	470±100 Ω Clear Hard-Coating
Operating Temperature Range	-10°C~60°C,20~85%RH. (Except for dew gathering)
Storage Temperature Range	-20°C ~70°C, 10%RH ~ 90%RH.(Except for dew gathering)
Surface Hardness	3H pencil pressure 1N/45
Hitting Durability	1,000,000 times (R8,hardness 60°,120gf)
Pen Sliding Durability	100,000 times (R0.8mm,with 120gf)
Insulation Impedance	\geq 20MΩ/25V(DC)
Light Transparency	≥80%-550nm
Linearity	≦1.5%
Linearity Force	10g~80g input with stylus pen. (R0.8mm)
Activation Force	50gf(Typical 20gf)less individual point on with stylus pen 9R0.8mm
Bouncing	≤10ms.
Impact Resistance	No damage when ψ 9mm steel ball is dropped on the surface from 30 cm height at 1 time.
Flexible pattern Heat Seal Peeling Strength	500gf/cm (peeling upward by 90deg)
Flexible pattern Bending Resistance	Bending 3 times by bending radius R1.0 mm The requirements in4-2shall be satisfied
Flexible Pattern Insert/Pull Out Resistance	5times at least .The requirements in 4-2shall be satisfied.
Vibration Resistance	Not in operation :The requirements in 3 to 4 shall be satisfied after sweep vibration of 2G15~55Hz(1min) is given for 30 min ,each in the directions of X,Y,Z.
Package Drop	No damage to the product.(1 corner edge,2ridges,4 surfaces ,drop from 50 cm height).
Static load resistance	After 4.5Kg load for 1 min is Applied to the center area (25c m ²)of the Touch panel ,the requirements in 3 and 4,shall be satisfied.



1.7.2 Electrical Characteristics

Item	Specification					
Operating Voltage	DC 5V. (Max : 7V DC)					
Bouncing	≦10ms					
Insulation Resistance	\geq 20MQ/25V(DC)					
Resistance Between	Direction X : $200 \Omega \sim 600 \Omega$.					
Terminals	Direction Y : $250 \Omega \sim 900 \Omega$.					
Linearity	X≦1.5%, Y≦1.5%					



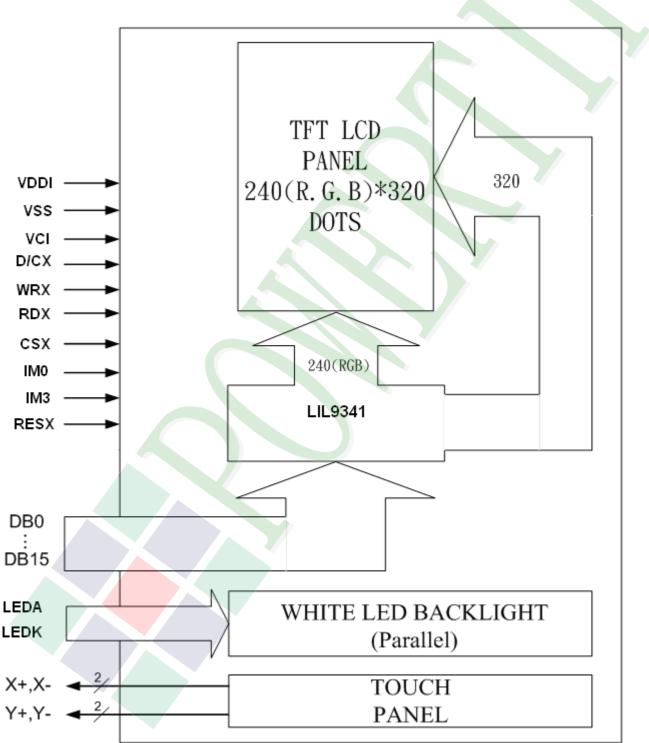
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram





2.2 Interface Pin Description

Pin No.	Symbol	Function
1	DB0	Bi-directional data bus.
2	DB1	Bi-directional data bus.
3	DB2	Bi-directional data bus.
4	DB3	Bi-directional data bus.
5	VSS	System ground.(0V)
6	VDDI	Low voltage power supply for interface logic circuits (1.65 ~ 3.3 V)
7	CSX	Chip select signal , Active "L".
8	D/CX	Command / Display data selection. 0 : Command , 1 : Display data.
9	WRX	8080- I system (WRX): Serves as a write signal and writes data at the rising edge.
10	RDX	8080- I system (RDX): Serves as a read signal and MCU
10	RDA	read data at the rising edge.
11	IM0	IM3=0,IM2=0,IM1=0,IM0=1,80 MCU 16-bit bus interface I , D[15:0]
12	X+	Touch Panel control pin.
13	Y+	Touch Panel control pin.
14	Х-	Touch Panel control pin.
15	Y-	Touch Panel control pin.
16	LEDA	Power supply for LED Backlight Anode input.
17	LEDk	Power supply for LED Backlight Cathode input.
18	NC	
19	NC	NC
20	NC	
21	IM3	IM3=0,IM2=0IM1=0,IM0=1,80 MCU 16-bit bus interface I , D[15:0]
22	DB4	Bi-directional data bus.
23	DB8	Bi-directional data bus.
24	DB9	Bi-directional data bus.
25	DB10	Bi-directional data bus.



26	DB11	Bi-directional data bus.
27	DB12	Bi-directional data bus.
28	DB13	Bi-directional data bus.
29	DB14	Bi-directional data bus.
30	DB15	Bi-directional data bus.
31	RESX	This signal will reset the device and must be applied to properly initialize the chip.Signal is active low.
32	VCI	High voltage power supply for analog circuit blocks (2.5 \sim 3.3 V)
33	VDDI	Low voltage power supply for interface logic circuits (1.65 ~ 3.3 V)
34	VSS	System ground.(0V)
35	DB5	Bi-directional data bus.
36	DB6	Bi-directional data bus.
37	DB7	Bi-directional data bus.



2.2.1 Refer Initial Code

void Initial_Main(void)

{

WriteCOM_Main(0x00,0xCF); WriteDAT_Main(0x00,0x00); WriteDAT_Main(0x00,0xD9); WriteDAT_Main(0x00,0x30);

WriteCOM_Main(0x00,0xED); WriteDAT_Main(0x00,0x64); WriteDAT_Main(0x00,0x03); WriteDAT_Main(0x00,0x12); WriteDAT_Main(0x00,0x81);

WriteCOM_Main(0x00,0xE8); WriteDAT_Main(0x00,0x85); WriteDAT_Main(0x00,0x00); WriteDAT_Main(0x00,0x78);

WriteCOM_Main(0x00,0xCB); WriteDAT_Main(0x00,0x39); WriteDAT_Main(0x00,0x2C); WriteDAT_Main(0x00,0x00); WriteDAT_Main(0x00,0x34); WriteDAT_Main(0x00,0x02);

WriteCOM_Main(0x00,0xF7); WriteDAT_Main(0x00,0x20);

WriteCOM_Main(0x00,0xEA); WriteDAT_Main(0x00,0x00); WriteDAT_Main(0x00,0x00);

WriteCOM_Main(0x00,0xC0); WriteDAT_Main(0x00,0x21);

WriteCOM_Main(0x00,0xC1); WriteDAT_Main(0x00,0x12); // For ILI9341



WriteCOM_Main(0x00,0xC5); WriteDAT_Main(0x00,0x32); WriteDAT_Main(0x00,0x3C);

WriteCOM_Main(0x00,0xC7); WriteDAT_Main(0x00,0xa3);

WriteCOM_Main(0x00,0x36); WriteDAT_Main(0x00,0x08);

WriteCOM_Main(0x00,0x3A); WriteDAT_Main(0x00,0x55);

WriteCOM_Main(0x00,0xB1); WriteDAT_Main(0x00,0x00); WriteDAT_Main(0x00,0x1B);

WriteCOM_Main(0x00,0xB6); WriteDAT_Main(0x00,0x0a); WriteDAT_Main(0x00,0xa2);

WriteCOM_Main(0x00,0xF6); WriteDAT_Main(0x00,0x01); WriteDAT_Main(0x00,0x30);

WriteCOM_Main(0x00,0xF2); WriteDAT_Main(0x00,0x00);

WriteCOM_Main(0x00,0x26); WriteDAT_Main(0x00,0x01);

WriteCOM_Main(0x00,0xe0); //set gamma WriteDAT_Main(0x00,0x0f); WriteDAT_Main(0x00,0x1c); WriteDAT_Main(0x00,0x19); WriteDAT_Main(0x00,0x08); WriteDAT_Main(0x00,0x0b); WriteDAT_Main(0x00,0x04);



WriteDAT_Main(0x00,0x4b); WriteDAT_Main(0x00,0x64); WriteDAT_Main(0x00,0x3e); WriteDAT_Main(0x00,0x09); WriteDAT_Main(0x00,0x15); WriteDAT_Main(0x00,0x08); WriteDAT_Main(0x00,0x16); WriteDAT_Main(0x00,0x0D); WriteDAT_Main(0x00,0x04);

WriteCOM Main(0x00,0xe1); //set gamma WriteDAT Main(0x00,0x00); WriteDAT Main(0x00,0x1a); WriteDAT Main(0x00,0x1e); WriteDAT_Main(0x00,0x03); WriteDAT Main(0x00,0x0f); WriteDAT Main(0x00,0x03); WriteDAT Main(0x00,0x35); WriteDAT Main(0x00,0x23); WriteDAT Main(0x00,0x45); WriteDAT Main(0x00,0x04); WriteDAT Main(0x00,0x0c); WriteDAT_Main(0x00,0x0b); WriteDAT Main(0x00,0x2b); WriteDAT Main(0x00,0x2e); WriteDAT_Main(0x00,0x05);

WriteCOM_Main(0x00,0x11);

Delay(120);

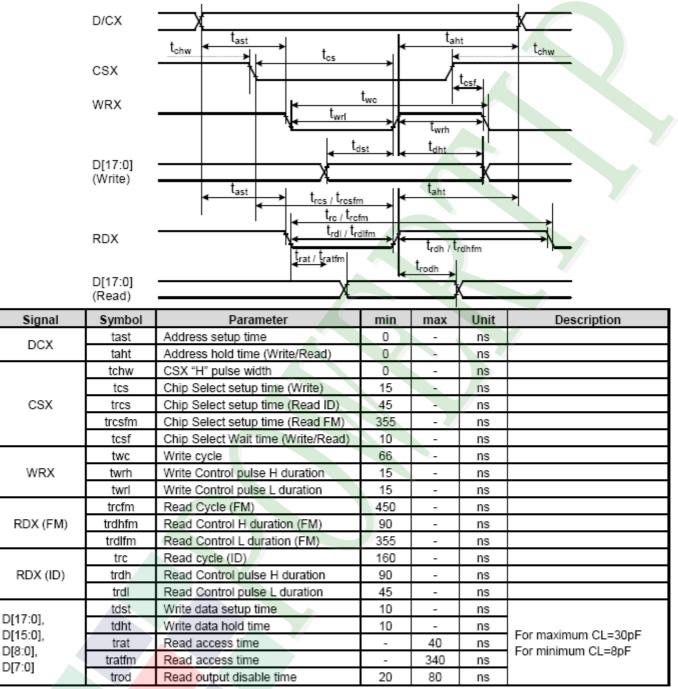
WriteCOM_Main(0x00,0x29);

}

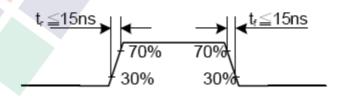


2.3 Timing Characteristics

80-System Bus Interface I

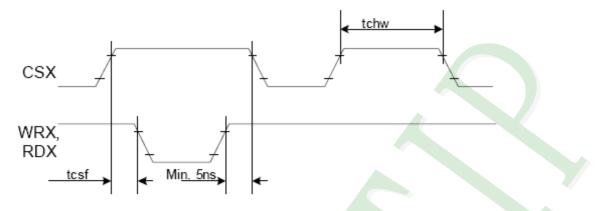


Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V



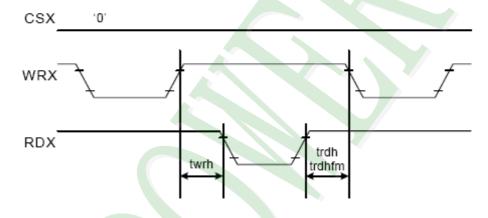


CSX timings :



Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:

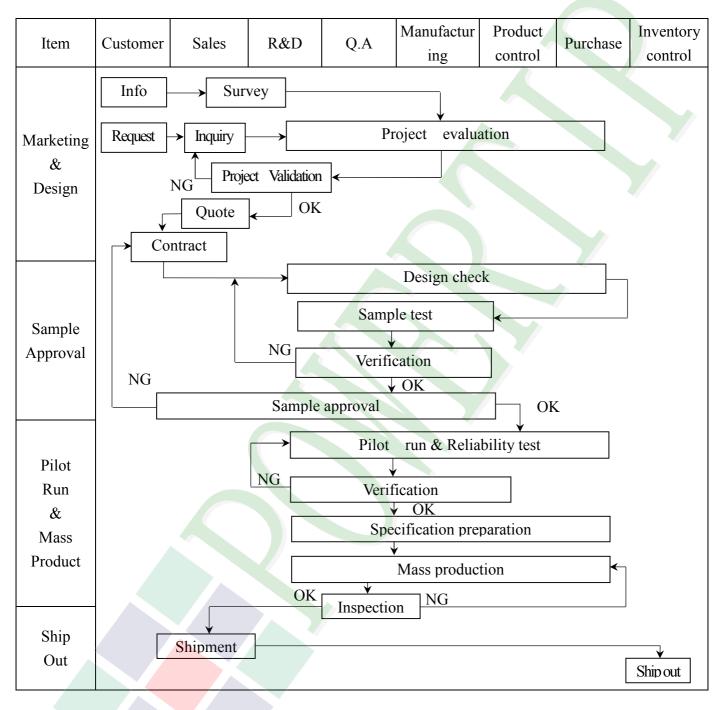


Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart

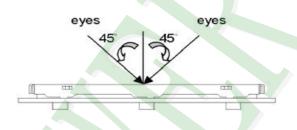




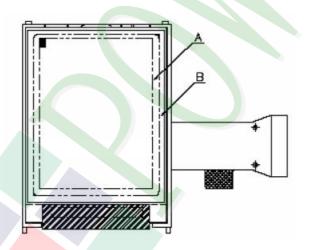
Item	Customer	Sales	R&D	Q.A	Manufactu ring	Product control	Purchase	Inventory control
Sales Service	Info	→ Claim sis report	[Trackin	Failure and Corrective			
Q.A Activity	 ISO 9001 Equipment Standardi 		n	4. E	ocess improv Education An	1 1		

3.2 Inspection Specification

- ◆Scope ∶ The document shall be applied to TFT-LCD Module for less than 3, 5″ (Ver.B01).
- ◆Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment : Gauge、MIL-STD、Powertip Tester、Sample
- ◆Defect Level : Major Defect AQL : 0,4 ; Minor Defect AQL : 1,5
- ♦OUT Going Defect Level : Sampling.
- ◆Standard of the product appearance test ∶
 - a. Manner of appearance test :
 - (1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.
 - (2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area : viewing area

B area : Outside of viewing area

(4). Standard of inspection : (Unit : mm)



♦Spe	Specification For TFT-LCD Module Less Than 3.5":					
NO	Item		Criterion			
		1. 1The part nur production.		t with work order of	Major	
01	Product condition	1.2 Mixed prod	uct types.		Major	
		1. 3 Assembled i	n inverse direction		Major	
02	Quantity	2. 1The quantity	is inconsistent wit	h work order of production.	Major	
03	Outline dimension	3.1 Product dimension and structure must conform to structure diagram.				
		4.1 Missing line	character and icon	n.	Major	
	Electrical Testing	4.2 No function	or no display.		Major	
04		4. 3 Display malfunction.				
		4.4 LCD viewin	ig angle defect.		Major	
		4. 5 Current con	sumption exceeds	product specifications.	Major	
			Item	Acceptance (Q'ty)		
	Dot defect (Bright dot \ Dark dot)		Bright Dot	≤ 2		
05		Dot	Dark Dot	≦ 3		
		Defect	Joint Dot	≦ 2		
			Total	≦ 3	Minor	
		5.1 Inspection p	oattern : full white	, full black , Red , Green and		
	On -display	blue screens.				
		5. 2 It is defined	as dot defect if def	čect area >1/2 dot.		
		5.3 The distance	e between two dot o	defect ≧5 mm.		



Specif	ication For TFT-LCD	Module Less Than 3.5″ :			(Ver.B01	
NO	Item	Criterion				
		6. 1 Round type (Non-display	or display) :			
		Dimension	Acceptanc	e (Q'ty)		
		(diameter ÷ Φ)	A area	B area		
	Black or white dot 、scratch 、	$\Phi \leq 0.15$	Ignore			
	contamination	$0.15 \ < \ \Phi \leq 0.20$	2			
	Round type	$0.20 < \Phi \leq 0.30$	2	Ignore		
		$\Phi > 0.30$	0			
06	Ý Y	Total	3		Minor	
	$\Phi = (x+y) / 2$ Line type $\downarrow \qquad \qquad$	6. 2 Line type(Non-display or Dimension Length (L) Width (W) $$ W ≤ 0 L ≤ 5.0 0.03 $<$ W ≤ 0 W $>0Total$	Accepta) A area 0.03 Ignore 0.05 3	nce (Q'ty) B area d Ignore		
		Dimension	Acceptance	(Q'ty)		
		(diameter ÷ Φ)	A area	B area		
	B .L.J.	$\Phi \leq 0.20$	Ignore			
07	Polarizer Bubble	$0.20 < \Phi \leq 0.50$	3	-	Minor	
		$\Phi > 0.50$	0	Ignore		
		Total	3			



◆Specification For TFT-LCD Module Less Than 3.5″: (Ver.B01) NO Level Item Criterion Symbols : X : The length of crack Y : The width of crack. Z : The thickness of crack W : terminal length t : The thickness of glass a : LCD side length _____ 8.1 General glass chip: 8.1.1 Chip on panel surface and crack between panels: Ζ 08 The crack of glass Minor [NG] [OK] Seal width Ζ х Y z Crack can't enter ≦1/2 t ≦ a viewing area Crack can't exceed the $1/2 t < Z \leq 2 t$ ≦ a half of SP width.



Spec	ification For TFT-LCD	Module Less	Than 3.5″ :			Ver.B01)
NO	Item		Cr	iterion		Level
		Z: The thi	igth of crack ickness of crack ckness of glass	W : term	width of crack. ainal length side length	
		8.1.2 Cor	ner crack:	Y Y		
		x	Y		Z	
		≦1/5 a	Crack can't e viewing are		$\leq 1/2 t$	
Section 2		≦1/5 a	Crack can't exc half of SP wie		$< Z \leq 2 t$	
08	The crack of glass				•	Mino
			sion over termin			
		8.2.1 Chi	p on electrode	pad:		
				7 X	Y Iz	
					······································	
		J W	X	- Me		
		WK			NIV.	
				COOL STOR		
				X		
			x	Y	Z	
		Front	≦ a	$\leq 1/2 \mathrm{W}$	≦ t	
		Back	≦ a	≦ W	$\leq 1/2 t$	



Symbols :X: The length of crack Z: The thickness of crack t: The thickness of glassY: The width of crack. W: terminal length a : LCD side length8. 2. 2 Non-conductive portion :WVV <tr< th=""><th>♦Spee</th><th>cification For TFT-L</th><th>CD Module Less Than 3.5″ :</th><th>(Ver.B01)</th></tr<>	♦Spee	cification For TFT-L	CD Module Less Than 3.5″ :	(Ver.B01)
08 The crack of glass Y: The width of crack. Y: terminal length a : LCD side length 08 The crack of glass a: LCD side length 08 The crack of glass Y: The width of crack. Y: terminal length a : LCD side length 08 The crack of glass Y: The width of crack. Y: terminal length a : LCD side length 08 The crack of glass Y: The width of crack. Y: terminal length a : LCD side length 08 The crack of glass Y: The width of crack. Y: terminal length a : LCD side length 08 The crack of glass Y: The width of crack. Y: terminal length a : LCD side length 08 The crack of glass Y: The width of crack. Y: terminal second terminal se	NO	Item	Criterion	Level
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	NO	Item The crack of	Criterion Symbols : X : The length of crack. X : The thickness of crack Y : The width of crack. Z : The thickness of crack Y : The width of crack. X : The thickness of glass a : LCD side length 8. 2. 2 Non-conductive portion : Image: colored provide length X : X X Z X X X X X X X X X X X Y Z Image: colored provide length X Y X Y Z Image: colored provide length X Y X Y X Y X Y X Y	Level



◆Specification For TFT-LCD Module Less Than 3.5″:

♦Spec	ification For TFT-	LCD Module Less Than 3.5″ :	(Ver.B01)
NO	Item	Criterion	Level
09		9. 1 Backlight can't work normally.	Major
	Backlight elements	9. 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
	diagram. 10. 2 No short circuits in components on PCB or FPC . 10. 3 Parts on PCB or FPC must be the same as on the procharacteristic chart .There should be no wrong missing parts or excess parts. General appearance 10. 4 Product packaging must the same as specified on pack specification sheet. 10. 5 The folding and peeled off in polarizer are not acceptal	10. 1 Pin type 、 quantity 、 dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC .	Major
			Major
		10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC) is ≤1.5 mm.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

(Ver.B01)

-+.					
NO.	TEST ITEM	TEST CONDITION			
1	High Temperature Storage Test	Keep in +80°C ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4 hrs.			
2	Low Temperature Storage Test	Keep in - 30℃ ±2℃ 96 hrs Surrounding temperature, then storage at normal condition 4hrs.			
3	High Temperature / High Humidity Storage Test	 Keep in +60 ℃ / 90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4 hrs. (Excluding the polarizer) 			
4	Temperature Cycling Storage Test	(30 min s ◀	s) (5mins) 10 C		
		Surrounding temperature, then storage at normal condition 4hrs.			
	ESD Test	Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/-		Contact Discharge: Apply 250 V with 5 times discharge for each polarity +/-	
5		 Temperature ambiance : 15°C ~35°C Humidity relative : 30%~60% Energy Storage Capacitance(Cs+Cd) : 150pF±10% 			
		 4. Discharge Resistance(Rd) : 330 Ω±10% 5. Discharge, mode of operation : Single Discharge (time between successive discharges at least 1 sec) 			
	(Tolerance if the output voltage indication : ±5%)				
6	Vibration Test (Packaged)	 Sine wave 10~55 Hz frequency (1 min/sweep) The amplitude of vibration :1.5 mm Each direction (X 、 Y 、 Z) duration for 2 Hrs 			
	Drop Test (Packaged)	Packi	ng Weight (Kg)	Drop Height (cm)	
			0 ~ 45.4	122	
7		4	5.4 ~ 90.8	76	
1			0.8 ~ 454	61	
			Over 454	46	
		Drop Direction : 1 corner / 3 edges / 6 sides each 1 time			



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is $25^{\circ}C \pm 5^{\circ}C$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

